



DATA-CENTRIC INNOVATION SUMMIT

AUGUST 8, 2018 | SANTA CLARA, CA



DATA-CENTRIC INNOVATION SUMMIT

INNOVATIONS FOR THE NEXT ERA OF CONNECTIVITY

ALEXIS BJÖRLIN

CORPORATE VICE PRESIDENT & GENERAL MANAGER
CONNECTIVITY GROUP

INNOVATION IN END-TO-END CONNECTIVITY



234
Access

233
Access

963
Access

238
Access

567
Access

238
Access

789
Access

156
Access

321
Access

135
Access

356
Access

478
Access

447
Access

267
Access

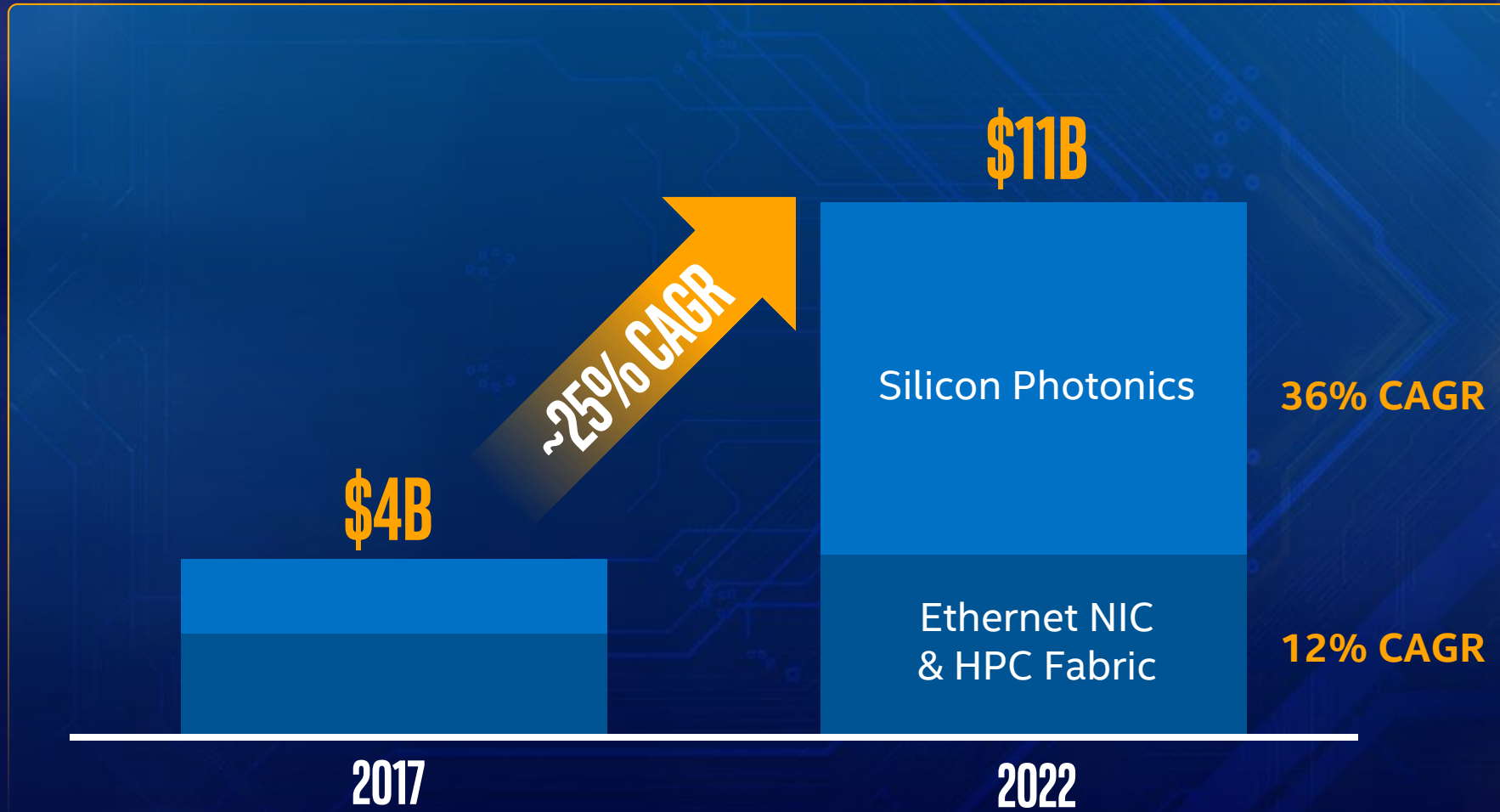
867
Access

DATA-CENTRIC
INNOVATION SUMMIT

#IntelDCISummit

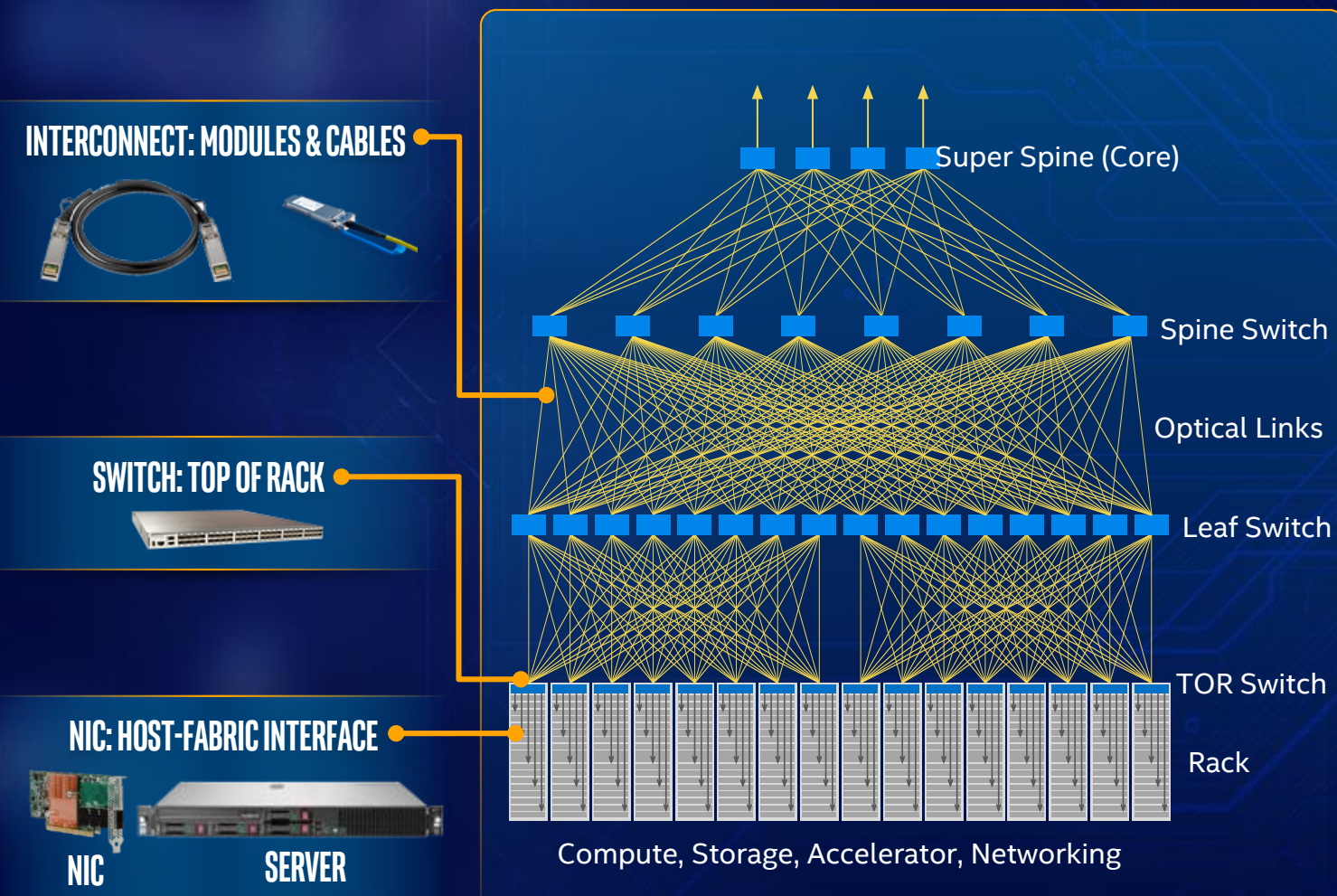


DATA CENTER CONNECTIVITY OPPORTUNITY



Forecasts are an amalgamation of analyst data and Intel analysis, based upon current expectations and available information, and are subject to change without notice. Silicon Photonics includes 100G+ links in the data center. Ethernet Switch Silicon TAM is not included in Connectivity chart (is included in Network Logic Silicon TAM).

CRITICALITY OF CONNECTIVITY TO COMPUTE



CONNECTIVITY DEFINES PERFORMANCE AT SCALE

- Improves Compute Performance, Efficiency & Scale
- Enables Storage & Accelerator Pools
- Enforces Platform Policy & Security
- Enables Warehouse → Global-scale Compute

SILICON PHOTONICS ENABLES SCALE

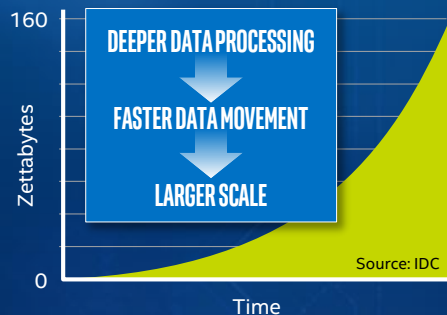
Spans Increasing Distance @ Increasing Speed

SMARTNIC ACCELERATES INFRASTRUCTURE WORKLOADS

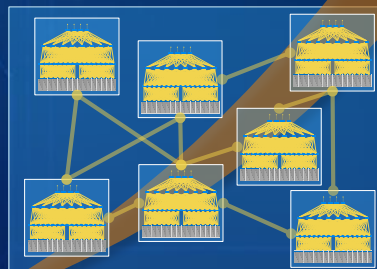
Network, Storage, Security

CRITICALITY OF CONNECTIVITY TO SCALE

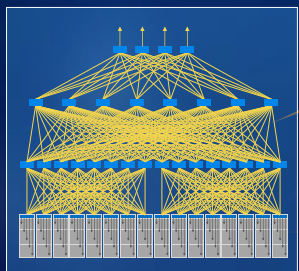
EXPONENTIAL DATA GROWTH → FABRIC INNOVATIONS



Global-Scale Fabric



Regional-Scale Fabric



Warehouse-Scale Fabric

CONNECTIVITY GROWING SUPER-LINEARLY
TO SUPPORT SCALE OUT OF COMPUTE & STORAGE

PER DATA CENTER...

GROWTH '15-'18¹

SERVERS

10X

SWITCHES

>15X

OPTICAL TRANSCEIVERS

>30X

INNOVATION IS REQUIRED

DATACENTER NETWORK INFLECTIONS: HOW WE WIN



INFRASTRUCTURE ACCELERATION IMPROVES PERFORMANCE

Strategy: Deliver Intelligent Platform Acceleration

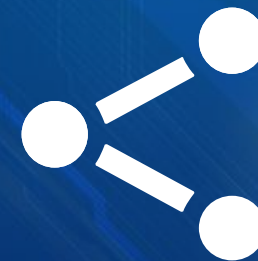
Performance-Optimized Solutions
Deliver Flexible Platform



CLOUD SCALE: THE BIG GET BIGGER

Strategy: Pioneer Next-gen Connectivity

Co-innovate with Cloud
Next Gen Product Collaboration



CRITICAL WORKLOADS EVOLVE THE NETWORK

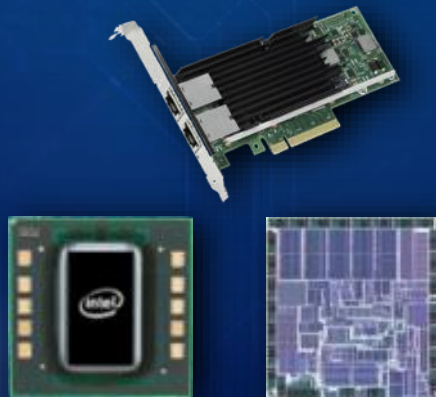
Strategy: Offer End-to-End Solutions

Optimize Connectivity Solutions
for AI, Storage
Optical IO Integration

INTEL® CONNECTIVITY PORTFOLIO

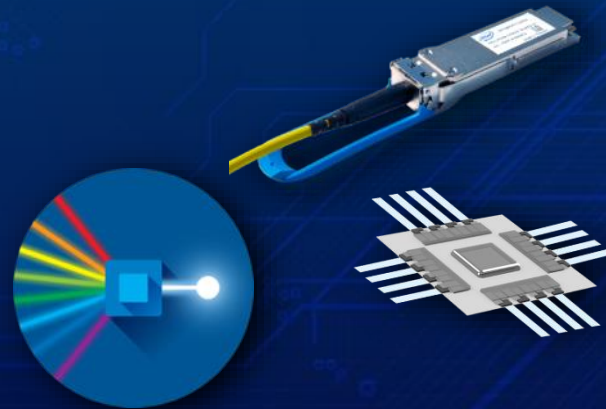
INTEL® ETHERNET

30+ YEAR LEADERSHIP



INTEL® SILICON PHOTONICS

LIGHTING UP SILICON



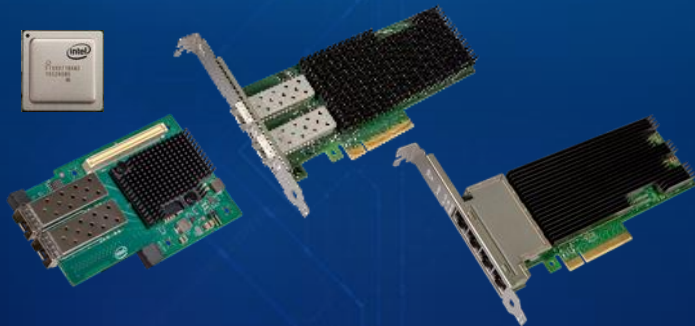
INTEL® OMNI-PATH FABRICS

LEADING HPC FABRICS



INTEL® ETHERNET PORTFOLIO & INTEL® PACS

FOUNDATIONAL NICs



Broad Portfolio
1GbE – 100GbE
30+ Years of Leadership
#1 MSS¹

NEW! SMARTNICs



Infrastructure Acceleration
Fully Validated
Solution Packages
Highly Programmable

PROGRAMMABLE ACCELERATION CARDS

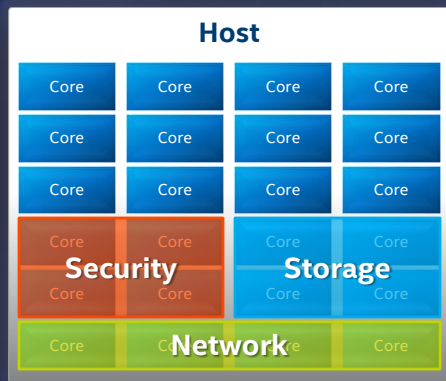


Versatile, Multi-Function
Acceleration
Intel-FPGA Based
Fully Programmable

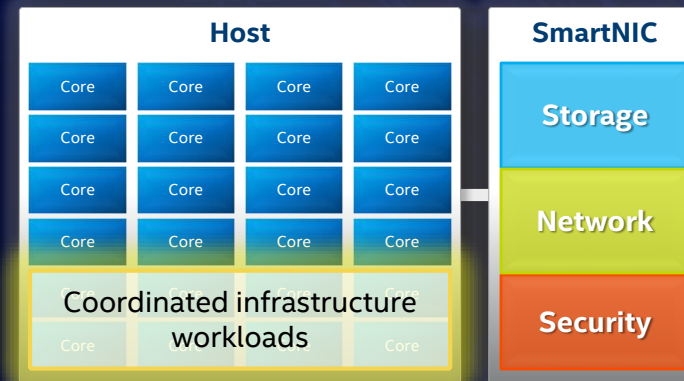
LEADING PORTFOLIO OF INTELLIGENT, CONFIGURABLE NETWORKING PRODUCTS

NEW INTEL – SMARTNIC PRODUCT FAMILY

Improved TCO and System Performance for Comms and Cloud Service Providers



Using Foundational NICs



Using SmartNICs



Cascade Glacier

INTEL LEADERSHIP

Industry First

World's First SmartNIC that Supports VM Live Migration Without Special Drivers¹

Highly Efficient

Minimizes CPU core Usage With Full Open vSwitch Acceleration On SmartNIC²

Programmability with Ease of Deployment

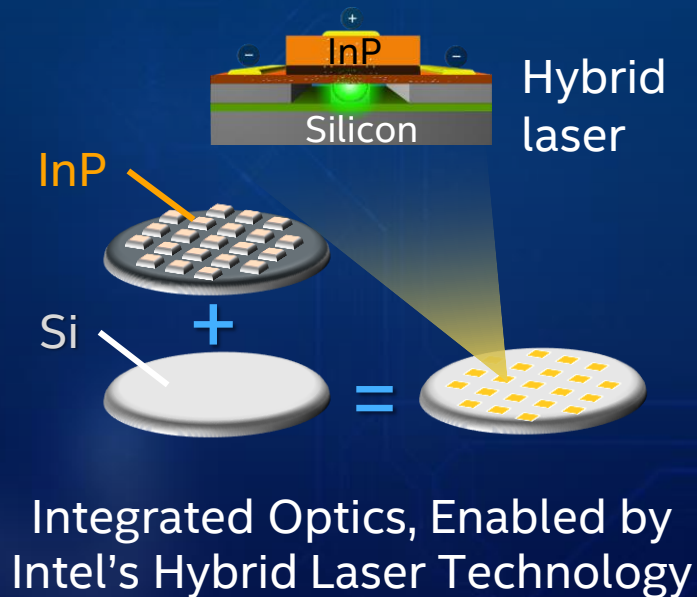
Unique Validated Solution Packages for Infrastructure Acceleration with Intel's Leading FPGAs

Cascade Glacier

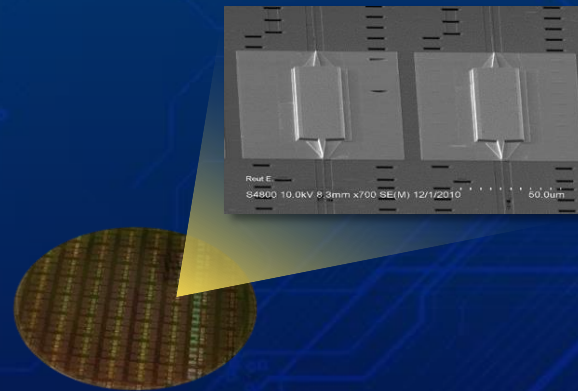
Sampling Now
2x25GbE Today
100GbE In Future

INTEL[®] SILICON PHOTONICS: OPTICS AT SILICON SCALE

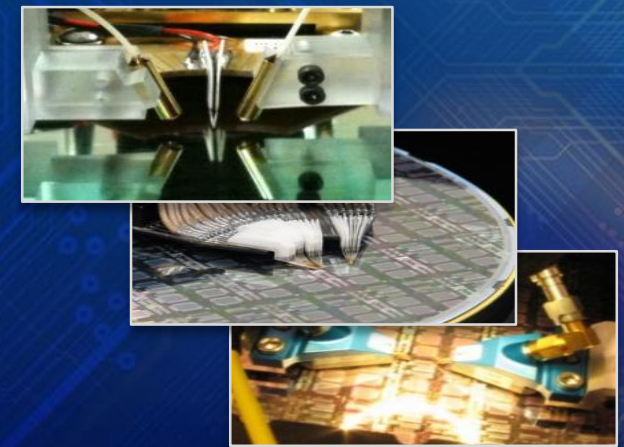
SILICON INTEGRATION



SILICON MANUFACTURING



SILICON SCALE



DIFFERENTIATED SOLUTION THROUGH HYBRID LASER APPROACH

INTEL® SILICON PHOTONICS - LIGHTING UP INTEL SILICON

INTERCONNECT: MODULES & CABLES



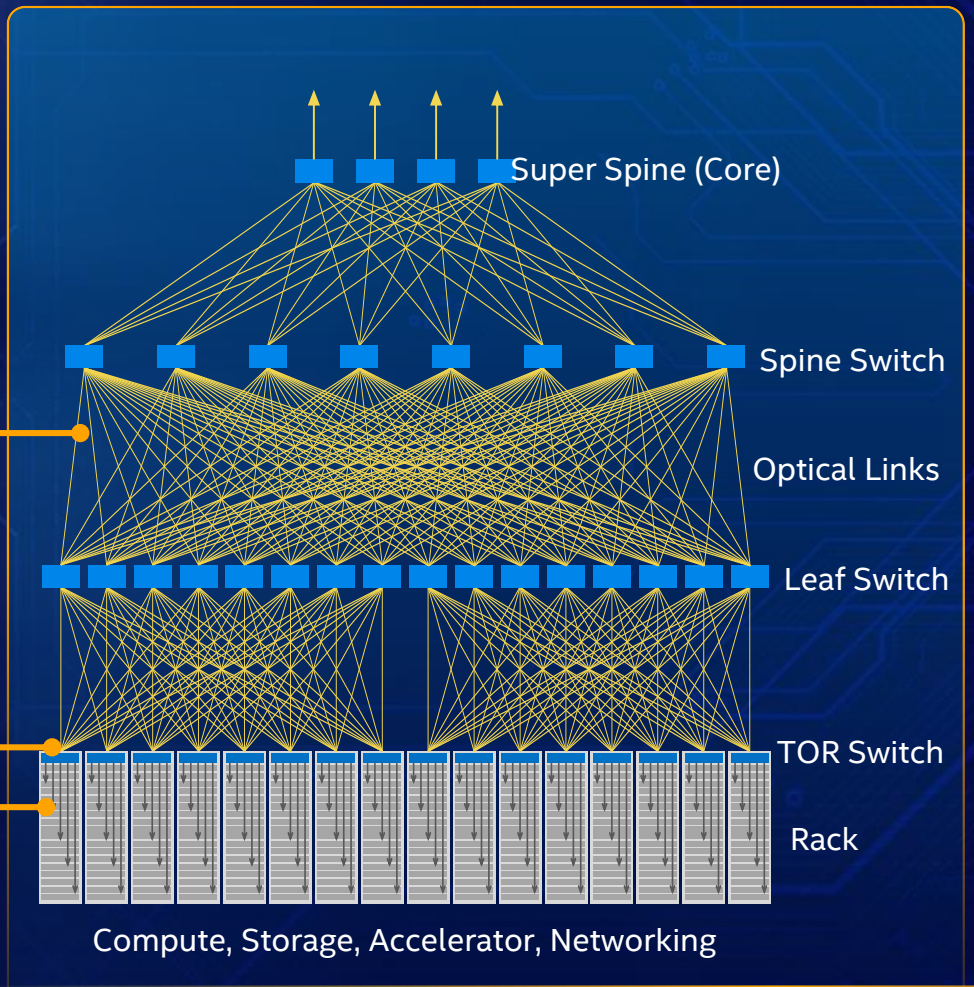
SWITCH: TOP OF RACK



NIC: HOST-FABRIC INTERFACE



NIC SERVER



ENABLING SCALE

Spans Increasing Distance at Increasing Speed
Integrated Optics + Intel Hybrid Laser = High Volume

GAINING MOMENTUM

Ramped Hyper-scale Cloud
Demonstrated 400G
Winning Awards  SEMI
New 5G Product

IN VOLUME PRODUCTION WITH MILLION+ UNIT RUN RATE

DATA-CENTRIC
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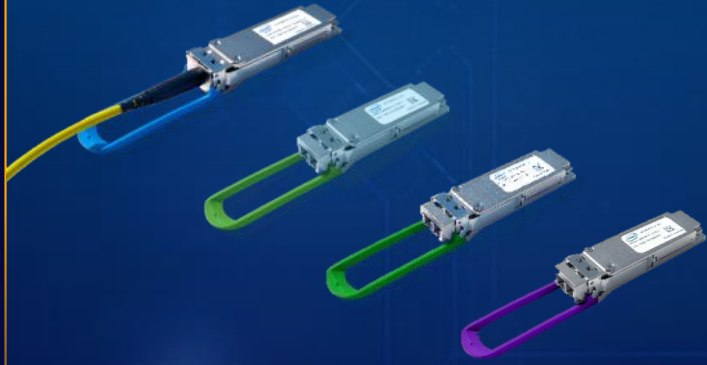
#IntelDCISummit



INTEL® SILICON PHOTONICS – NEW GROWTH BUSINESS

SILICON-BASED PHOTONIC PLATFORM MANUFACTURED BY INTEL

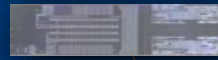
IN PRODUCTION AT CLOUD SCALE
100G Optical Module Portfolio



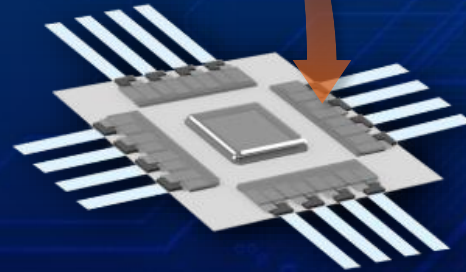
400G in Development

LIGHTING UP INTEL SILICON

Highly-integrated Photonics



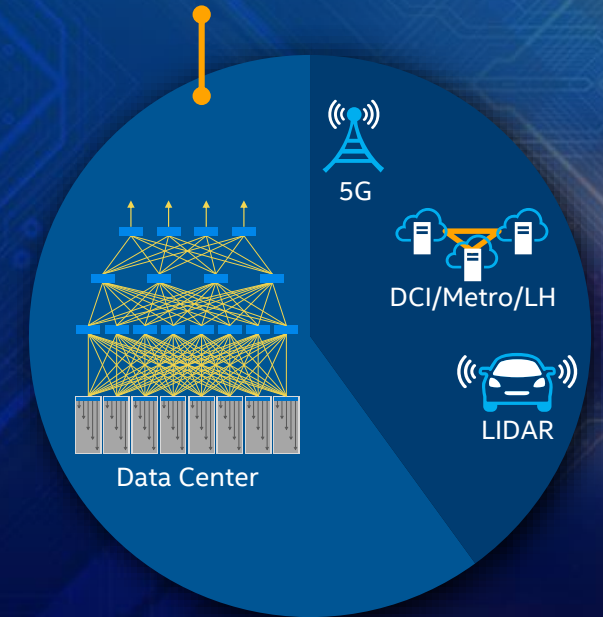
Co-packaged with Logic Silicon



Reduces Power, Costs & Complexity
Increases Density¹

OFFERS SIGNIFICANT GROWTH FOR DCG

~\$7B Datacenter TAM in 2022²



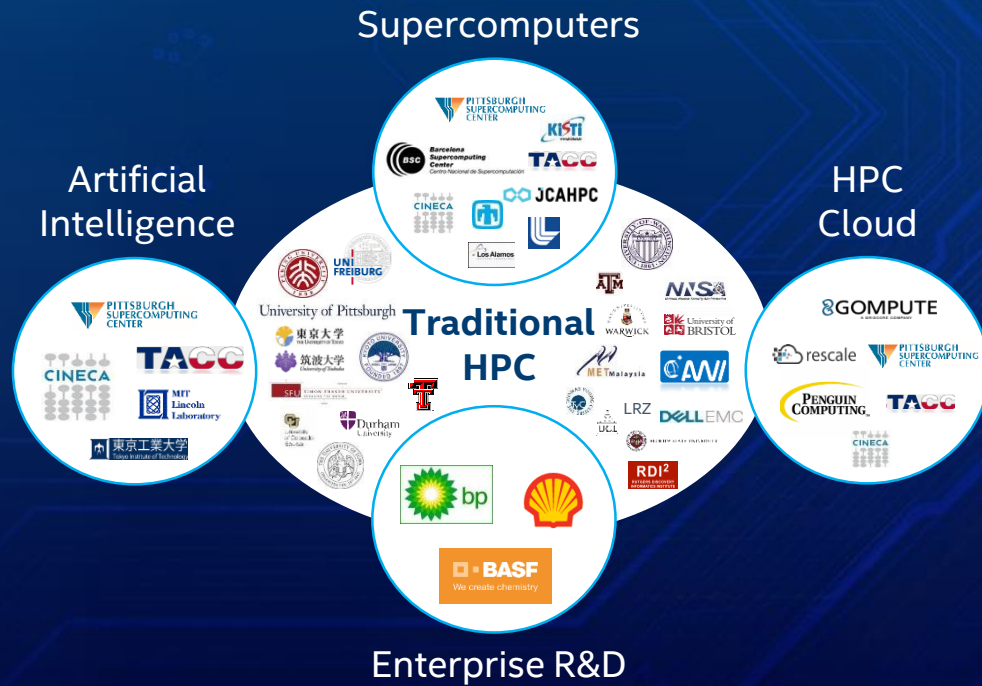
INTEL® OMNI-PATH ARCHITECTURE MARKET SUCCESS

END-TO-END HPC FABRIC SOLUTION

Silicon, Systems, Software



DEPLOYED IN ALL REGIONS & ALL SEGMENTS



TOP500 MOMENTUM

Record # of Systems / FLOPS

Up ~36% In Total FLOPs Since Nov '17

50% 100Gb Nodes

18% of Top100 Systems

27% of Top100 Green Systems



Source: Top500.org June '18

SUMMARY: CONNECTIVITY IS CRITICAL TO COMPUTE

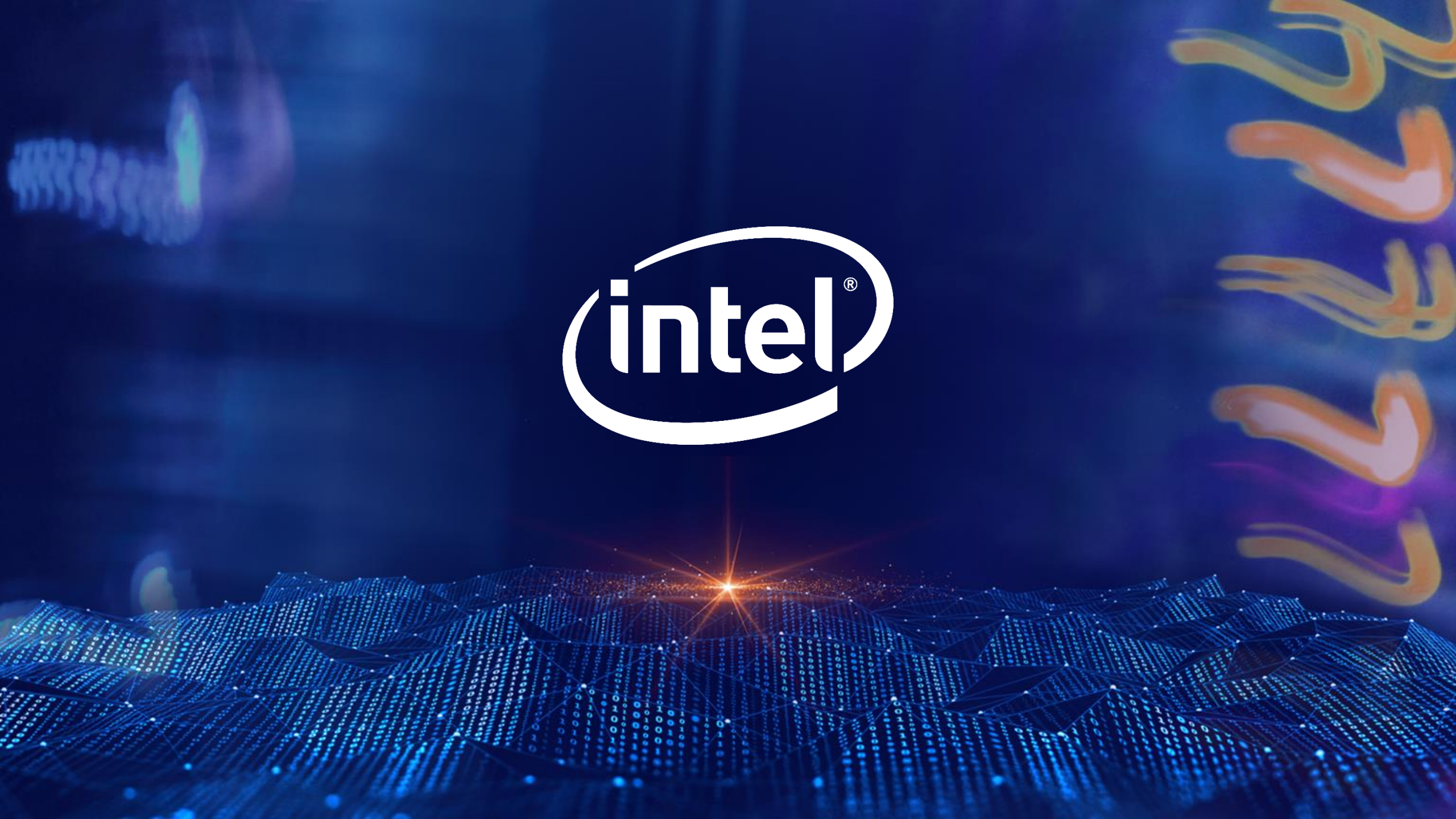
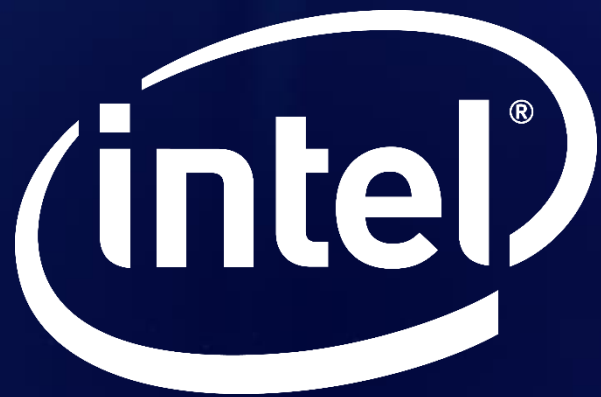
CONNECTIVITY **UNLEASHES THE POWER OF COMPUTE AT SCALE**

CONNECTIVITY IS AN **\$11B+ DATACENTER OPPORTUNITY**

SMARTNICS AND SILICON PHOTONICS **REVOLUTIONIZE NETWORK EFFICIENCY**

INTEL'S E2E **CONNECTIVITY PORTFOLIO LEADS THE INDUSTRY**

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